

PLATED GROUND FEATURES FOR INTEGRATED LEAD SUSPENSIONS

Abstract

A method for forming an electrical interconnect on an integrated lead suspension or suspension component of the type formed from a laminated sheet of material having a stainless steel layer, a conductive lead layer and an insulating layer separating the stainless steel and conductive lead layers. An aperture is formed through at least the insulating layer to expose the stainless steel layer at an interconnect site. An interconnect mask is applied around the interconnect site. Conductive material is electroplated onto the stainless steel layer at the interconnect site to form a plated interconnect. The mask is then removed. The method is used to form an interconnect bond pad on the same side of the stainless steel layer as the conductive lead layer in one embodiment. In another embodiment the aperture is formed through the insulator layer and the stainless steel layer, and conductive material is built up on the stainless steel layer during the electroplating step until it meets and plates onto the conductive lead layer to form a stainless steel side interconnect. In yet another embodiment the aperture is formed through the insulator layer and the conductive lead layer, and conductive material is built up on the stainless steel layer during the electroplating step until it meets and plates onto the conductive lead layer to form a conductive lead side interconnect.